



MEMS/NEMS Sensors: Fabrication and Application, Volume III

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Message from the Guest Editor

As a result of the ever-expanding applications of micro- and nano-electromechanical systems (NEMS/MEMS) as sensors and actuators, interest in their development has rapidly expanded over the past decade. Encompassing various excitation and readout schemes, the MEMS/NEMS devices transduce physical parameter changes, such as temperature, mass, or stress, caused by alterations in desired measurands, to electrical signals that can be further processed. Some common examples of NEMS/MEMS sensors include pressure sensors, accelerometers, magnetic field sensors, microphones, radiation sensors, and particulate matter sensors.

Despite a long history of development, the fabrication of novel MEMS/NEMS devices still poses unique challenges due to their requirement for a suspended geometry. Many new fabrication techniques have been proposed to overcome these challenges. However, further development of these techniques is still necessary, as newer materials such as compound semiconductors and two-dimensional materials are finding their way in various MEMS/NEMS applications, with more complex structures and potentially smaller dimensions.





Editor-in-Chief

Message from the Editor-in-Chief

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